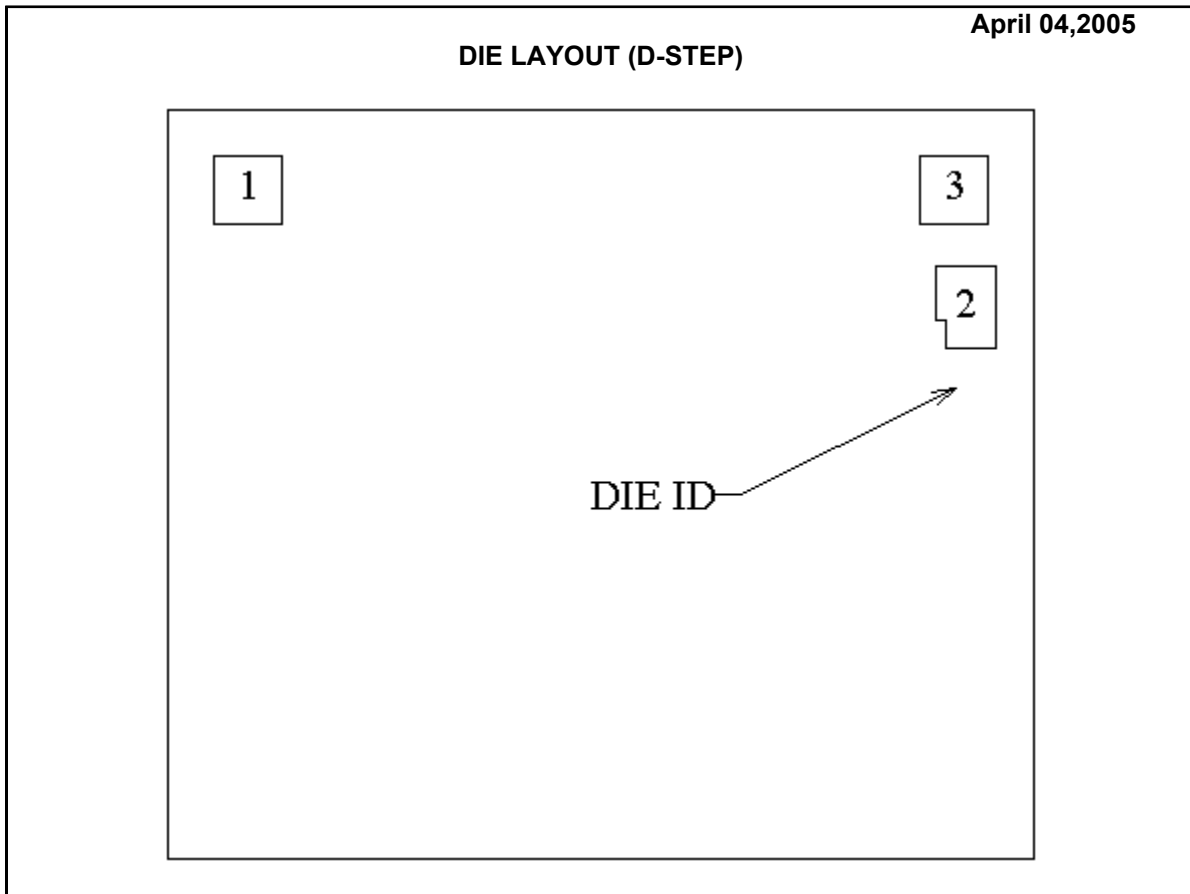


**LM113 MD8 MW8
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DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	113D	Bond Pad Opening Size (min)	117 μ m x 117 μ m
Die Step	D	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	125mm	Back Side Metal	Gold
Die Size (Drawn)	1499 μ m x 1295 μ m 59.0mils x 51.0mils	Back Side Connection	Floating
Thickness	330 μ m Nominal		
Min Pitch	203 μ m Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (D-Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
SIGNAL	PAD#	XY COORDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
+	1	-610	508	117	x	117
NC	2	629	305	104	x	142
-	3	610	508	117	x	117

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